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INFORMATION DISCLOSURE STATEMENT PTO-1449		Atty. Docket No. ABE-034	10/55076	Serial No. Not assigned
		Applicant: Eiji KAMIYAMA et al.		
		Filing Date: September 27, 2005	Group: 1763	Not assigned

U.S. PATENT DOCUMENTS

Examiner's Initial		Document No.	Date	Name	Class	Sub Class	Filing Date If appropriate
/RC/	UA	5,882,987 A	03/16/99	Srikrishnan	438	458	
/RC/	UB	6,140,210 A	10/31/00	Aga et al.	438	458	
/RC/	UC	6,372,609 B1	04/16/02	Aga et al.	438	459	
/RC/	UD	5,374,564 A	12/20/94	Bruel	437	24	
/RC/	UE	6,020,252 A	02/01/00	Aspar et al.	438	458	
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Examiner's Initial		Document No.	Date	Country	Translation Yes/No/Partial
/RC/	FA	11-121377 A	04/30/99	JP	Abstract
/RC/	FB	11-102848 A	04/13/99	JP	Abstract
/RC/	FC	2000-124092 A	04/28/00	JP	Abstract
/RC/	FD	2003-17723 A	01/17/03	JP	Abstract & Translation
/RC/	FE	2004-80035 A	03/11/04	JP	Abstract & Translation
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Examiner's Initial		
/RC/	DA	Auberton-Hervé, A.J. et al., "SMART-CUT®: The Basic Fabrication Process for UNIBOND® SOI Wafers," <i>IEICE TRANS ELECTRON</i> , Vol. E80 C, No. 3, 1997, pp. 358-363.
/RC/	DB	Tong, Q.Y. et al., "Semiconductor Wafer Bonding: Science and Technology"; November, 1998:printout of website http://www3.interscience.wiley.com:8100/WileyCDA/WileyTitle/productCd-0471574813,descCd-description.html?print=true .
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Examiner:	/Roberts Culbert/	Date Considered:	08/05/2007
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KTK/jbf

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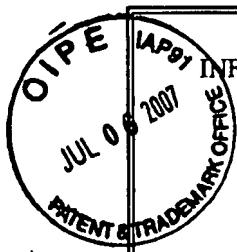
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/RC/	DB	Tong, Q.Y. et al, "Semiconductor Wafer Bonding: Science and Technology"; November, 1998:printout of website http://www3.interscience.wiley.com:8100/WileyCDA/WileyTitle/productCd-0471574813,descCd-description.html?print=true .
	DC	

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INFORMATION DISCLOSURE STATEMENT
PTO-1449

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/RC/	FC	1 085 562 A2	03/21/01	EP	
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	DB	
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